



Click [here](#) for the 3D model.

| General Information | |
|--------------------------|---|
| Series | SMD Auto COG HV Flex |
| Style | SMD Chip |
| Description | SMD, MLCC, FT-CAP, Ultra-Stable, Automotive Grade |
| Features | FT-CAP, Ultra-Stable, Automotive Grade |
| RoHS | Yes |
| Termination | Flexible Termination |
| Marking | No |
| Qualifications | AEC-Q200 |
| AEC-Q200 | Yes |
| Typical Component Weight | 42 mg |
| Shelf Life | 78 Weeks |
| MSL | 1 |

| Dimensions | |
|------------|-----------------|
| Chip Size | 1206 |
| L | 3.3mm +/-0.4mm |
| W | 1.6mm +/-0.35mm |
| T | 1.6mm +/-0.25mm |
| S | 1.5mm MIN |
| B | 0.6mm +/-0.25mm |

| Packaging Specifications | |
|--------------------------|--------------------------|
| Packaging | T&R, 180mm, Plastic Tape |
| Packaging Quantity | 2000 |

| Specifications | |
|--|------------------------|
| Capacitance | 220 pF |
| Measurement Condition | 1 MHz 1.0Vrms |
| Tolerance | 5% |
| Voltage DC | 1500 VDC |
| Dielectric Withstanding Voltage | 1,800 VDC |
| Temperature Range | -55/+125°C |
| Temp. Coefficient | COG |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 30 ppm/C, 1MHz 1.0Vrms |
| Dissipation Factor | 0.1% 1 MHz 1.0Vrms |
| Aging Rate | 0% Loss/Decade Hour |
| Insulation Resistance | 100 GOhms |

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